



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN) ADDENDUM

PCN #: L9910-03R1	DATE: May 22, 2000	MEANS OF DISTINGUISHING CHANGED DEVICES:
Product Affected: Selected 3.3V Double Density Logic FCT Devices (See Below For Detail Part Nos.)		<input type="checkbox"/> Product Mark
Manufacturing Location Affected: N/A		<input type="checkbox"/> Back Mark
Date Effective: June 22, 2000		<input checked="" type="checkbox"/> Date Code Prefix from "N" or "L" to "X"
		<input type="checkbox"/> Other

Contact: Bimla Paul	Attachment:: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
Title: Product Assurance Manager	
Phone #: 408-654-6419	
Fax #: 408-492-8362	Samples: Available upon request
E-mail: bimla.paul@idt.com	

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process For selected 3.3V Double Density Logic FCT products, IDT will be migrating to a new die revision for process consolidation. There is no data sheet specifications or package change. This PCN Addendum replaces PCN # L9910-03.
- Assembly Process
- Equipment
- Material
- Testing Additional affected part numbers are: 74FCT163373, 163374, 163543, 163601 & 163952
- Manufacturing Site Please see attachment for the complete affected part numbers.
- Data Sheet
- Other

RELIABILITY/QUALIFICATION SUMMARY:

Qualification and reliability data will be available upon request.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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PCN Summary

PCN Type:

Design Change
Change to Fab Process

Commodity

Logic

Forecast or Execute

Execute

Planned or Unplanned

Unplanned

Data Sheet Change

No Change

Detail of Change

For selected 3.3V Double Density Logic FCT products, IDT will be migrating to a new die revision for process consolidation. There is no data sheet specification or package change.

The affected part numbers are: 54/74FCT163344, 163501, 163827, 163646, 163244, 163245, 74FCT163373, 163374, 163543, 163601 and 163952

Process / Design Changes

Current Die

Replacment Die

54/74FCT163344	54/74FCT163646
54/74FCT163501	54/74FCT163244
54/74FCT163827	54/74FCT163245
74FCT163543	74FCT163373
74FCT163601	74FCT163374
74FCT163952	

Wafer Fab Technology	CMOS 7	CMOS 7	CMOS 8
Feature Size	0.8 μ m	0.8 μ m	0.6 μ m
Minimum Gate Oxide	140 Å	140 Å	140 Å
Wafer Size	6"	6"	6"
Die Dimension (sq mils)	11.4	6.28	7.76
Fab Facility	Fab 2	Fab 2	Fab 2
Datecode Prefix Designator	N	L	X

Conversion schedule (Estimated)

PCN # L9910-03R1

Sample Availability

Production Shipments

54/74FCT163344
54/74FCT163501

Available
Available

February 1, 2000
February 1, 2000



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54/74FCT163646	Available	February 1, 2000
54/74FCT163827	Available	February 1, 2000
54/74FCT163244	Available	February 1, 2000
54/74FCT163245	Available	February 1, 2000
74FCT163373	Available	June 22, 2000
74FCT163374	Available	June 22, 2000
74FCT163543	Available	June 22, 2000
74FCT163601	Available	June 22, 2000
74FCT163952	Available	June 22, 2000

Qualification Data

Test Vehicle: 65501X/65373X/65244X/65646X

	Lot #1	Lot #2	Lot #3
Operating Life Test (Dynamic) (1000 Hrs @ 125°C, Vcc = 3.3V)	116/0	116/0	116/0
Temperature cycling (-65°C to +150°C, 500cyc)	45/0	45/0	45/0
Bake and Ball Shear Test	20/0	20/0	20/0
Die Shear Test	3/0	3/0	3/0
ESD: HMB Category II (>2kV) Mil-Std 883, Method 3015	3/0	3/0	3/0
ESD: CDM	3/0	3/0	3/0
Latch-up JEDEC Std 17	10/0	N/A	N/A
Electrical characterization	10/0	N/A	N/A
I/O capacitance	5/0	N/A	N/A

Characterization Data:

Characterization Data is available upon request.